



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

A. Samsung Part Number

- Samsung P/N : CL10C150J
- CL10C150JB81PNC CAP, 15pF, 50V, ±5%, C0G, 0603
- Description : CA
- AEC-Q 200 Specified

		<u>CL</u> ①	<u>10</u> ②	<u>С</u> З	<u>150</u> ④	<u>J</u> (5)	<u>B</u> 6	<mark>8</mark> ⑦	<u>1</u> ⑧	<u>P</u> 9	<u>N</u> 10	<u>C</u> 1		
1	Series	Samsung Multi-layer Ceramic Capacitor												
2	Size	0603 (inch c	ode)		L:	1.6	± 0.1	mm			W:		0.8 ± 0.1	mm
3	Dielectric	C0G				8	Inner	electr	ode			Ni		
4	Capacitance	15 pF					Term	inatio	n			Cu		
5	Capacitance	±5 %					Platin	g				Sn ′	100%	(Pb Free)
	tolerance					9	Produ	ict				Auto	omotive	
6	Rated Voltage	50 V				10	Grade	e code	•			Star	ndard	
\bigcirc	Thickness	0.8 ± 0.1	mm			1	Packa	aging				Car	dboard Typ	e, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition					
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150℃					
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25pF whichever is larger						
	Q : 700 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles					
	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	1 cycle condition :					
	Q : 700 min	-55+0/-3℃(15±3min) -> Room Temp(1min.)					
	IR : More than 10,000№ or 500№×μF	-> 125+3/-0°C(15±3min) -> Room Temp(1min.)					
	Whichever is Smaller						
Destructive Physical	No Defects or abnormalities	Per EIA 469					
Analysis							
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle					
	Capacitance Change :	Heat (25~65 $^\circ \!\! C)$ and humidity (80~98%), Unpowered					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	measurement at 24±2hrs after test conclusion					
	Q : 312.5 min						
	IR : More than 10,000№ or 500№×μF						
	Whichever is Smaller						
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 °C/85%RH, Rated Voltate and 1.3~1.5V,					
	Capacitance Change :	Add 100kohm resistor					
	within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger	Measurement at 24±2hrs after test conclusion					
	Q : 150 min	The charge/discharge current is less than 50mA.					
	IR : More than 500№ or 25№×μF						
	Whichever is Smaller						
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125°C, 200% Rated Voltage,					
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion					
	within $\pm 3.0\%$ or $\pm 0.3 \text{pF}$ whichever is larger	The charge/discharge current is less than 50mA.					
	Q : 312.5 min						
	IR : More than 10,000₩ or 500₩Ω×μF						
	Whichever is Smaller						

	Performance	Test condition						
External Visual	No abnormal exterior appearance	Microscope (10)						
Physical Dimensions	Within the specified dimensions	Using The calipers						
Mechanical Shock	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	Three shocks in each direction should be applied along3 mutually perpendicular axes of the test specimen (18 shocks)PeakvalueDurationWaveVelocity1,500G0.5msHalf sine4.7m/sec.						
Vibration	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2000Hz.						
Appearance : No abnormal exterior appearance Solder Heat Capacitance Change : within ±2.5% or ±0.25 pF whichever is larger Q, IR : initial spec.		Solder pot : 260±5℃, 10±1sec.						
Thermal Shock	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	-55 ℃/+125 ℃. Note: Number of cycles required-300, Maximum transfer time-20 sec, Dwell time-15min. Air-Air						
ESD	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger Q, IR : initial spec.	AEC-Q200-002						
Solderability	95% of the terminations is to be soldered evenly and continuously	 a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C solder : a solution ethanol and rosin 						
Electrical Characterization	Capacitance : Within specified tolerance Q : 700 max. IR(25℃) : More than 100,000MΩ or 1,000MΩ×μF IR(125℃) : More than10,000MΩ or 100MΩ×μF Whichever is Smaller Dielectric Strength	The Capacitance /Q should be measured at 25 ℃, 1™±10%, 0.5~5Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25 ℃, @125 ℃ for 60~120 sec. Dielectric Strength : 250% of the rated voltage for 1~5 seconds						
Board Flex	Appearance : No abnormal exterior appearance Capacitance Change : within ±5.0% or ±0.5pF whichever is larger	Bending to the limit (3mm) for 5 seconds						
Terminal Strength(SMD)	Appearance : No abnormal exterior appearance Capacitance Change : within ±2.5% or ±0.25pF whichever is larger	10N, for 60±1 sec.						
Beam Load	Destruction value should not be exceed Chip Length < 2.5mm a) Chip Thickness > 0.5mm : 20N b) Chip Thickness ≤ 0.5mm : 8N	Beam speed 0.5±0.05mm/sec						
Temperature Characterisitcs	C0G (From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)							

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

 * For the more detail Specification, Please refer to the Samsung MLCC catalogue.